

IN THE CLAIMS:

Please amend the claims as follows:

1. (Previously Amended) An electronic device assembly for a substrate having circuits thereon comprising:
an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;
a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame formed by one of compression molding and injection molding, a portion of each of the plurality of lead fingers formed for contacting a circuit of said circuits of said substrate;
an adhesive attaching a portion of said integrated circuit semiconductor die to a portion of said conductive plastic lead frame;
at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to at least one lead finger of said plurality of lead fingers of said conductive plastic lead frame; and
encapsulating material for encapsulating at least a portion of said integrated circuit semiconductor die and for encapsulating at least a portion of at least one lead of said conductive plastic lead frame.
3. (Previously Amended) An electronic device assembly for a substrate having a plurality of circuits thereon comprising:
an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;
a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame including a plastic lead frame structure having a conductive polymeric material located on at least a portion of said plurality of lead fingers, a portion of each of the plurality of lead fingers formed for contacting a circuit of said circuits of said substrate;

Serial No. 09/944,015

an adhesive for attaching a portion of said integrated circuit semiconductor die to a portion of said conductive plastic lead frame;
at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to at least one lead finger of said conductive plastic lead frame; and
encapsulating material for encapsulating at least a portion of said integrated circuit semiconductor die and for encapsulating at least a portion of said at least one lead of said conductive plastic lead frame.